

MOTOROLA

SEMICONDUCTOR

TECHNICAL DATA

BUT14

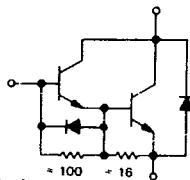
SWITCHMODE SERIES NPN SILICON POWER DARLINGTON TRANSISTORS WITH BASE-EMITTER SPEEDUP DIODE

The BUT 14 Darlington transistor is designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line-operated switchmode applications such as:

- AC and DC Motor Controls
- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Fast Turn-Off Times

300 nS Inductive Fall Time at 25°C (Typ)
1.3 μS Inductive Storage Time at 25°C (Typ)

- Operating Temperature Range - 65 to 200°C

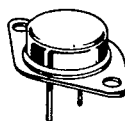


25 AMPERES NPN SILICON POWER DARLINGTON TRANSISTORS

850 VOLTS
175 WATTS

Designer's Data for "Worst Case" Conditions

The Designer's Data Sheet permits the design of most circuits entirely from the information presented. Limit data - representing device characteristics boundaries - are given to facilitate "worst case" design.



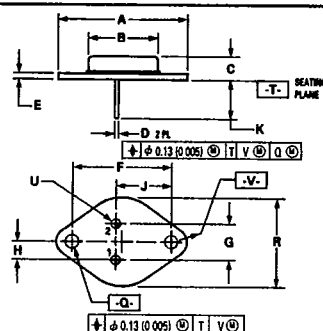
MAXIMUM RATINGS

Rating	Symbol	BUT14	Unit
Collector-Emitter Voltage	$V_{CE(sus)}$	500	Vdc
Collector-Emitter Voltage	V_{CEV}	850	Vdc
Emitter Base Voltage	V_{EB}	10	Vdc
Collector Current	I_C	25	Adc
- Continuous	I_{CM}	35	
- Peak (1)			
Base Current	I_B	5	Adc
- Continuous	I_{BM}	7.5	
- Peak (1)			
Free Wheel Diode:			
Forward current - Continuous	I_F	25	Adc
- Peak	I_{FM}	35	
Total Power Dissipation (@ $T_C = 25^\circ\text{C}$)	P_D	175	Watts
Derate above 25°C		100	W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	- 65 to + 200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.0	°C/W
Maximum Lead Temperature for Soldering Purpose: 1/8" from Case for 5 Seconds	T_L	275	°C

(1) Pulse Test. Pulse Width = 5 ms, Duty Cycle ≤ 10%



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1987.
2. CONTROLLING DIMENSION: INCH.
3. ALL RULES AND NOTES ASSOCIATED WITH REFERENCED TO-204AA OUTLINE SHALL APPLY.

	MILLIMETERS			INCHES		
DIM	MIN	MAX	MIN	MAX		
A	—	39.37	—	1.550		
B	—	21.08	—	0.830		
C	6.25	8.25	0.250	0.325		
D	0.97	1.09	0.038	0.043		
E	1.40	1.77	0.055	0.070		
F	30.15 BSC		1.187 BSC			
G	10.92 BSC		0.430 BSC			
H	5.46 BSC		0.215 BSC			
J	16.89 BSC		0.665 BSC			
K	11.18	12.19	0.440	0.480		
Q	3.64	4.19	0.151	0.165		
R	—	26.67	—	1.050		
U	4.83	5.33	0.190	0.210		
V	3.64	4.19	0.151	0.165		

STYLE 1:
PIN 1: BASE
2: EMITTER
CASE: COLLECTOR

CASE 1-06
TO-204AA
(TO-3)

ELECTRICAL CHARACTERISTICS (TC = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Sustaining Voltage (Table 1) (IC = 100 mA, IB = 0)	VCE(sus)	500	—	—	Vdc
Collector Cutoff Current (VCEV = Rated Value, VBE(off) = 1.5 Vdc) (VCEV = Rated Value, VBE(off) = 1.5 Vdc, TC = 100°C)	ICEV	—	—	0.2 2.0	mA _{dc}
Emitter Cutoff Current (VEB = 2.0 V, IC = 0)	IEBO	—	—	175	mA _{dc}

SECOND BREAKDOWN

Second Breakdown Collector Current with base forward biased	IS/b		See Figure 16	
Clamped Inductive SOA with Base Reverse Biased	RBSOA		See Figure 17	

ON CHARACTERISTICS (1)

DC Current Gain (IC = 8 A, VCE = 5 V) (IC = 16 A, VCE = 5 V)	hFE	30 15	— —	— —	
Collector-Emitter Saturation Voltage (IC = 8 A, IB = 0.4 A) (IC = 16 A, IB = 1.6 A) (IC = 20 A, IB = 2.0 A) (IC = 25 A, IB = 5 A)	VCE(sat)	— — — —	— — — —	2.0 3.0 3.5 5.0	Vdc
Base-Emitter Saturation Voltage (IC = 8 A, IB = 0.4 A) (IC = 16 A, IB = 1.6 A) (IC = 20 A, IB = 2 A)	VBE(sat)	— — —	— — —	2.5 2.9 3.3	Vdc
Diode Forward Voltage (IF = 20 A)	VF	—	—	4.0	Vdc

SWITCHING CHARACTERISTICS

Inductive Load, Clamped (Table 1)

Storage Time	TC = 25°C	See Table 1 IC = 16 A	ts	—	1.3	2.8	μs
Fall Time			tf	—	0.3	0.8	μs
Storage Time	TC = 100°C	IB1 = 1.6 A VBE(off) = 5 V	ts	—	1.5	—	μs
Fall Time			tf	—	0.35	—	μs

(1) Pulse Test PW = 300 μs, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

FIGURE 1 — DC CURRENT GAIN

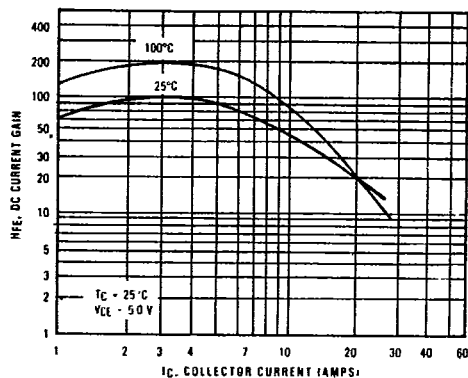


FIGURE 2 — COLLECTOR SATURATION REGION

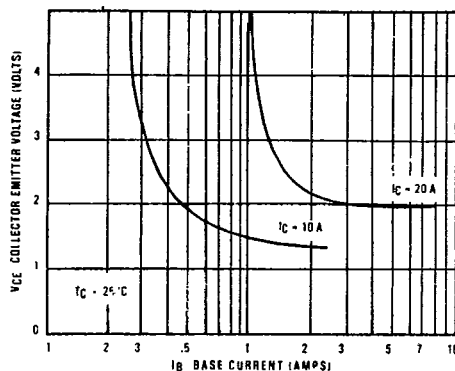


FIGURE 3 — COLLECTOR-EMITTER SATURATION VOLTAGE

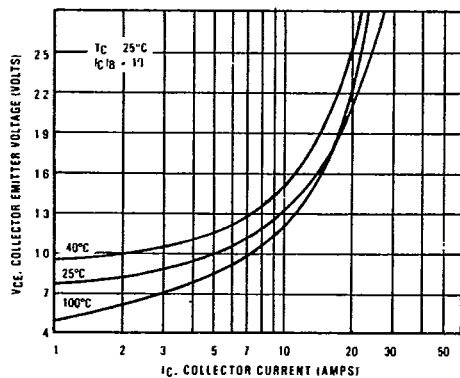


FIGURE 4 — BASE-EMITTER VOLTAGE

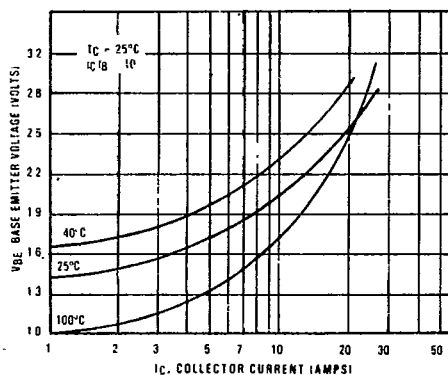


FIGURE 5 — THERMAL RESPONSE

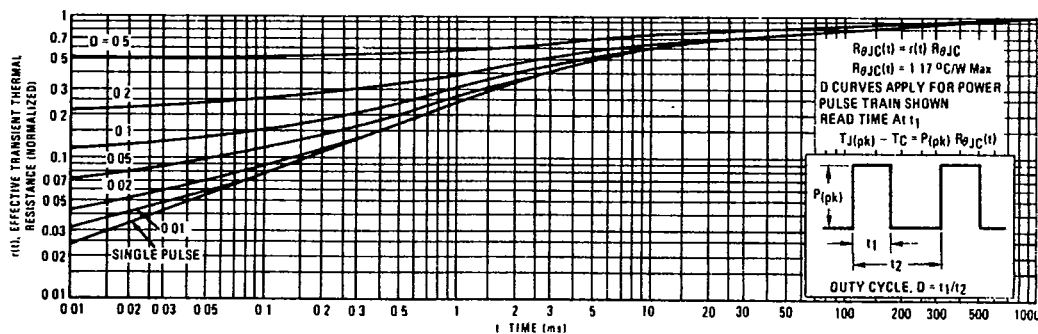


TABLE I - TEST CONDITIONS FOR DRIVER AND LOAD					
INPUT CONDITIONS	VCEQ(us)	RMSOA AND INDUCTIVE SWITCHING			
 Pulse width at Amax $I_C = 100\text{mA}$				TEST CIRCUIT for FREE-WHEEL DIODE 	
CIRCUIT VALUES	Lcoil 10 mH VCC 10 V RCoil 0.7 Ω VClamp VCeQ(us) I _c 100 mA	Lcoil 180 μH RCoil 0.05 Ω VCC 10 V			
TEST CIRCUITS	INDUCTIVE TEST CIRCUIT		OUTPUT WAVEFORMS		
See Above for Detailed Conditions			t₁ Adjusted to Obtain I_C t₁ = Lcoil(ICM)/VCC t₂ = Lcoil(ICM)/V_{Lamp} Test Equipment Tektronix 475 or Equivalent		

Figure 2 is a graph showing the relationship between the time constant, T , in microseconds (μs), and the forced gain, BF FORCED GAIN. The y-axis is logarithmic, ranging from 1 to 10 μs . The x-axis is linear, ranging from 1 to 10. A curve is plotted for $I_C = 10 A$ & $25 A$. The curve starts at approximately (1, 4.2) and decreases as BF FORCED GAIN increases. At BF FORCED GAIN = 2, T is approximately 4.2 μs . At BF FORCED GAIN = 5, T is approximately 3.0 μs . At BF FORCED GAIN = 10, T is approximately 2.5 μs . The graph also includes the conditions $T_C = 25^\circ C$ and $V_{BE(off)} = -5 V$.

Figure 1 is a graph showing the relationship between switching time (t_s in μs) and load current (I_L in A) for the 2N3638 PNP silicon transistor. The y-axis is logarithmic, ranging from 1 to 10. The x-axis is linear, ranging from 1 to 10. Two curves are plotted: one for $I_C = 10 A$ and one for $I_C = 25 A$. Both curves show that switching time decreases as load current increases. The $I_C = 25 A$ curve is consistently higher than the $I_C = 10 A$ curve. A note specifies $T_C = 25^\circ C$ and $I_C I_B = 5$.

FREE-WHEEL DIODE CHARACTERISTICS

FIGURE 10 - FREE WHEEL DIODE MEASUREMENTS

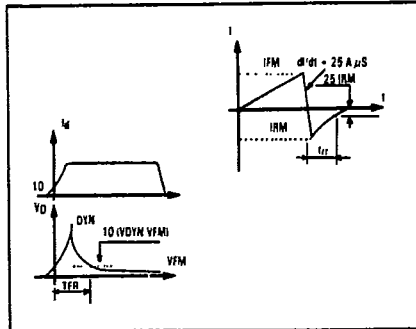


FIGURE 11 - FORWARD VOLTAGE

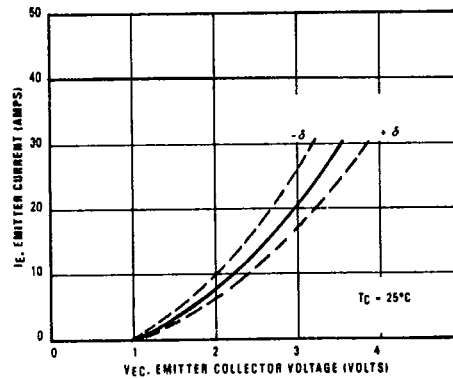


FIGURE 12 - FORWARD MODULATION VOLTAGE

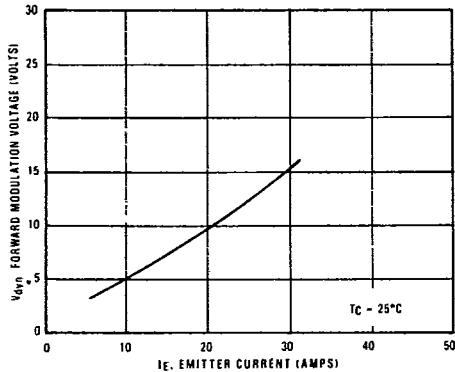


FIGURE 13 - PEAK REVERSE RECOVERY CURRENT

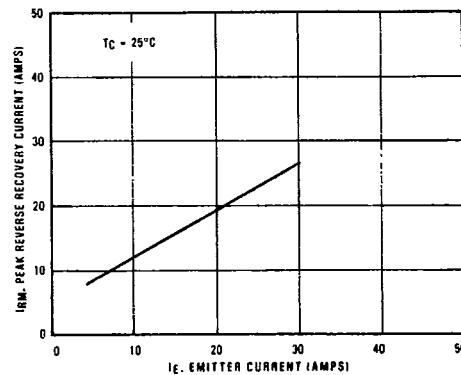


FIGURE 14 - FORWARD RECOVERY TIME

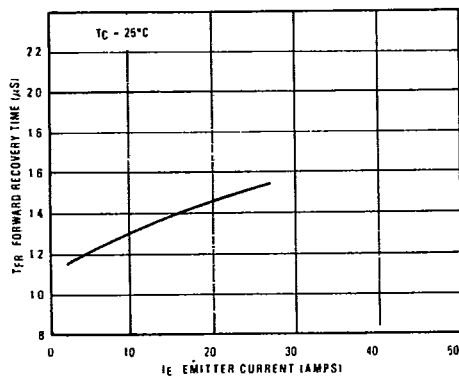
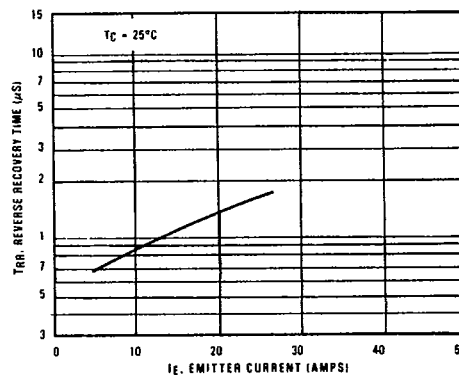


FIGURE 15 - REVERSE RECOVERY TIME



The Safe Operating Area figures shown in Figures 16 and 17 are specified for these devices under the test conditions shown.

FIGURE 16 - SAFE OPERATING AREA

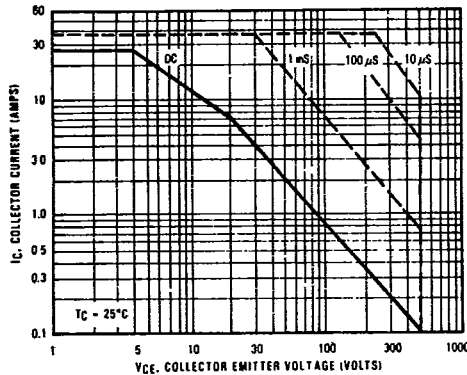
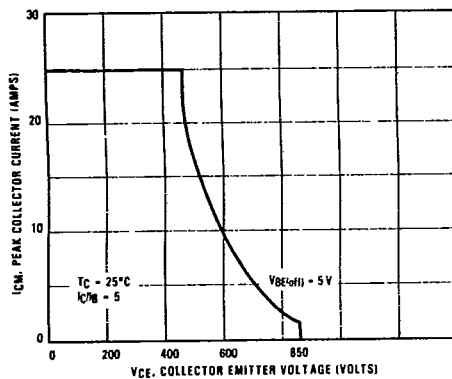


FIGURE 17 - REVERSE BIAS SAFE OPERATING AREA



SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C - V_{CE} limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subject to greater dissipation than the curves indicate.

The data of Figure 16 is based on $T_C = 25^\circ\text{C}$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \geq 25^\circ\text{C}$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 16 may be found at any case temperature by using the appropriate curve on Figure 18.

$T_{J(pk)}$ may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 17 gives the RBSOA characteristics.

FIGURE 18 - POWER DERATING

